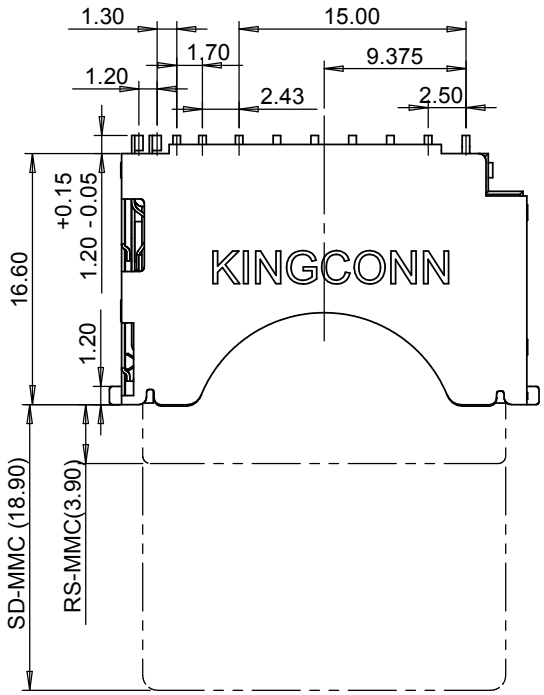
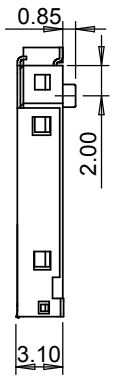
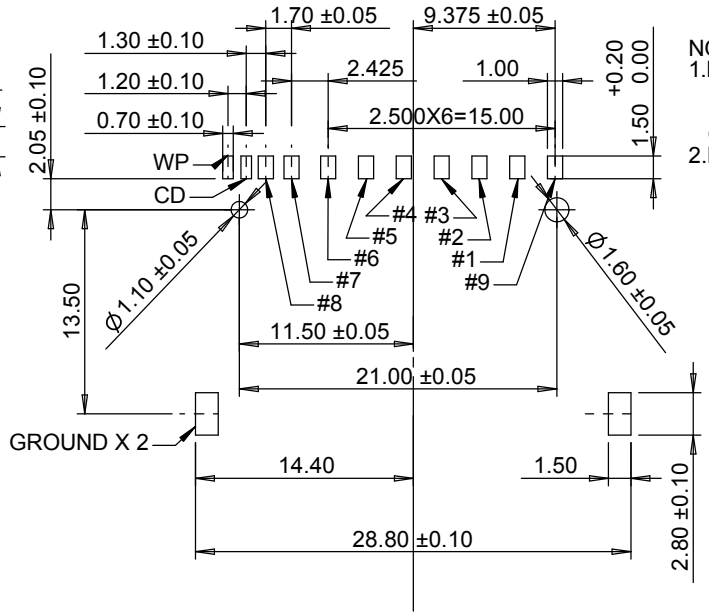
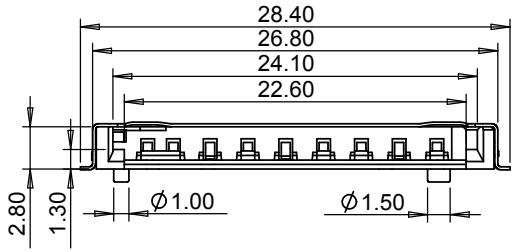
| 更改 REV | 設 變 內 容 MODIFICATION |
|---|---|
| A | ECN00281 |
| B | ECN00542 |
| C | ECN00567 |
| D | ECN00638 |
| E | ECN00854 |

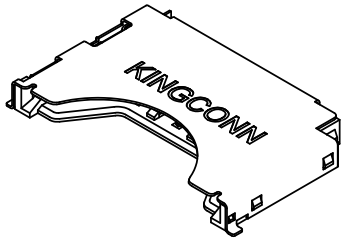



NOTES:
1.MATERIAL:
INSULATOR:HIGH TEMPRATURE THERMOPLASTIC, UL94V-0,BLACK
CONTACT:PHOSPHOR BRONZE
2.PART NO:SDCN-X0-1010
PLATING :
F:CONTACT AREA:Gold Flash Plated Over Ni
SOLDER AREA : Tin Plated OVER Ni
B:CONTACT AREA:10μ" Au Plated Over Ni
SOLDER AREA : Tin Plated OVER Ni

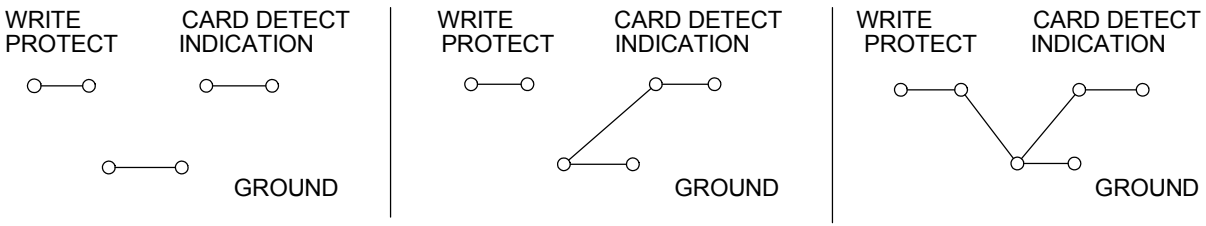



Pin Assignment:

| PIN NO : | NAME |
|---|---|
| SD & MMC #1 | DAT3 |
| SD & MMC #2 | CMD |
| SD & MMC #3 | GND |
| SD & MMC #4 | VCC |
| SD & MMC #5 | CLK |
| SD & MMC #6 | GND |
| SD & MMC #7 | DAT0 |
| SD & MMC #8 | DAT1 |
| SD & MMC #9 | DAT2 |

CIRCUIT:




| GENERIAL TOLERANCE | |
|---|---|
| X.± 0.50 | X.°± 5° |
| .X± 0.30 | .X°± 2° |
| .XX± 0.20 | .XX°± 1° |

**KINGCONN** 皇海科技股份有限公司

名 稱(TITLE): SD CARD CONNECTOR

| 單 位(UNIT) | 料 號(PART NO.) | 圖 號(DWG NO.) |
|---|---|---|
| mm | SDCN-X0-1010 | SDCN-X0-1010-E |

| 審 核(APPROVAL) | 核 對(CHECKED) | 製 圖(DRAWN) | 比 例 SCALE 3:1 | 張數 SHEET 1/1 |
|---|---|---|---|---|
| | | | 角 法 PROJ. | 更改 REV E |